

128Kx32 SRAM MODULE, SMD 5962-93187 & 5962-95595

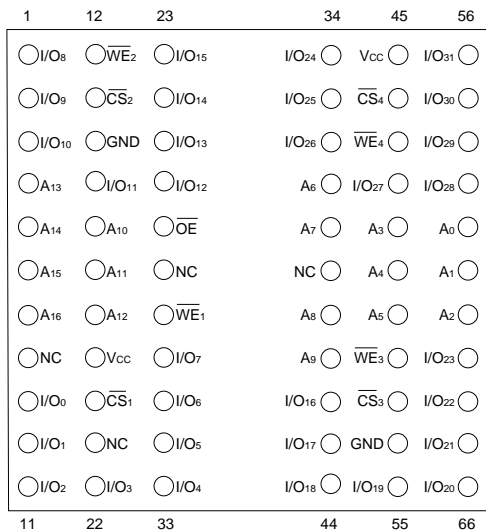
FEATURES

- Access Times of 15, 17, 20, 25, 35, 45, 55ns
- MIL-STD-883 Compliant Devices Available
- Packaging
 - 66 pin, PGA Type, 1.075" square, Hermetic Ceramic HIP (Package 400)
 - 68 lead, 40mm Low Profile CQFP, 3.56mm (0.140") (Package 502), Package to be developed.
 - 68 lead, 22.4mm Low Profile CQFP, 4.57mm (0.180"), (Package 509)
- Organized as 128Kx32; User Configurable as 256Kx16 or 512Kx8
- Low Power Data Retention - only available in G2T/E package type
- Commercial, Industrial and Military Temperature Ranges
- 5 Volt Power Supply
- Low Power CMOS
- TTL Compatible Inputs and Outputs
- Built in Decoupling Caps and Multiple Ground Pins for Low Noise Operation
- Weight:
 - WS128K32-XG2TX / EDI8C32128C-E - 8 grams typical
 - WS128K32-XH1X / EDI8C32128C-G - 13 grams typical
 - WS128K32-XG4TX - 20 grams typical
- All devices are upgradeable to 512Kx32

NOTE: For non-SMD new designs, please use the WS128K32-XXX part number for inquiries and orders.

FIG. 1 PIN CONFIGURATION FOR WS128K32N-XH1X AND EDI8C32128C-G

TOP VIEW



PIN DESCRIPTION

I/O0-31	Data Inputs/Outputs
A0-16	Address Inputs
WE1-4	Write Enables
CS1-4	Chip Selects
OE	Output Enable
Vcc	Power Supply
GND	Ground
NC	Not Connected

BLOCK DIAGRAM

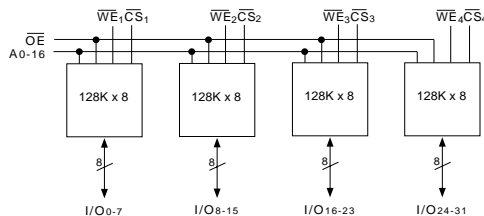
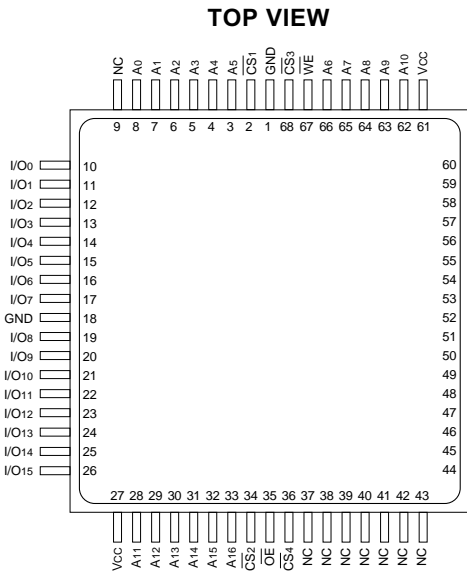




FIG. 2 PIN CONFIGURATION FOR WS128K32-XG4TX



PIN DESCRIPTION

I/O0-31	Data Inputs/Outputs
A0-16	Address Inputs
WE	Write Enables
CS1-4	Chip Selects
OE	Output Enable
VCC	Power Supply
GND	Ground
NC	Not Connected

BLOCK DIAGRAM

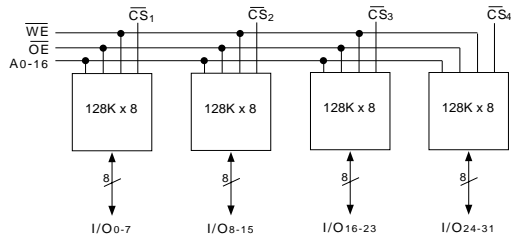
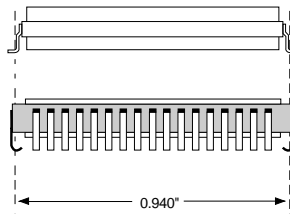
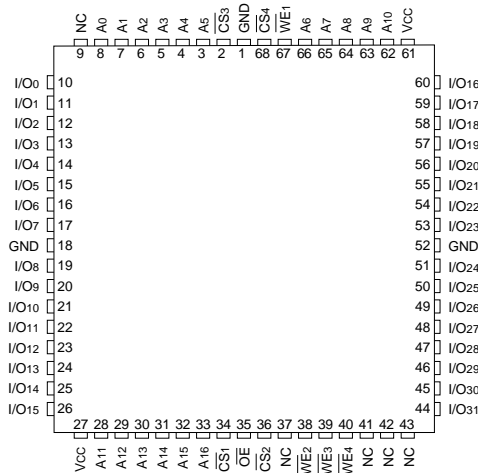


FIG. 3 PIN CONFIGURATION FOR WS128K32-XG2TX AND EDI8C32128C-E

TOP VIEW

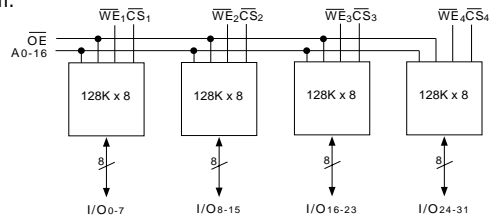


The White 68 lead G2T CQFP fills the same fit and function as the JEDEC 68 lead CQFJ or 68 PLCC. But the G2T has the TCE and lead inspection advantage of the CQFP form.

PIN DESCRIPTION

I/O0-31	Data Inputs/Outputs
A0-16	Address Inputs
WE1-4	Write Enables
CS1-4	Chip Selects
OE	Output Enable
VCC	Power Supply
GND	Ground
NC	Not Connected

BLOCK DIAGRAM





ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Min	Max	Unit
Operating Temperature	T _A	-55	+125	°C
Storage Temperature	T _{STG}	-65	+150	°C
Signal Voltage Relative to GND	V _G	-0.5	V _{CC} +0.5	V
Junction Temperature	T _J		150	°C
Supply Voltage	V _{CC}	-0.5	7.0	V

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Min	Max	Unit
Supply Voltage	V _{CC}	4.5	5.5	V
Input High Voltage	V _{IH}	2.2	V _{CC} + 0.3	V
Input Low Voltage	V _{IL}	-0.3	+0.8	V
Operating Temp. (Mil.)	T _A	-55	+125	°C

TRUTH TABLE

\overline{CS}	\overline{OE}	\overline{WE}	Mode	Data I/O	Power
H	X	X	Standby	High Z	Standby
L	L	H	Read	Data Out	Active
L	X	L	Write	Data In	Active
L	H	H	Out Disable	High Z	Active

CAPACITANCE

(T_A = +25°C)

Parameter	Symbol	Conditions	Max	Unit
\overline{OE} capacitance	C _{OE}	V _{IN} = 0 V, f = 1.0 MHz	50	pF
\overline{WE} ₁₋₄ capacitance HIP (PGA) H1/G CQFP G4 CQFP G2T/E	C _{WE}	V _{IN} = 0 V, f = 1.0 MHz	20 50 20	pF
\overline{CS} ₁₋₄ capacitance	C _{CS}	V _{IN} = 0 V, f = 1.0 MHz	20	pF
Data I/O capacitance	C _{I/O}	V _{I/O} = 0 V, f = 1.0 MHz	20	pF
Address input capacitance	C _{AD}	V _{IN} = 0 V, f = 1.0 MHz	50	pF

This parameter is guaranteed by design but not tested.

DC CHARACTERISTICS

(V_{CC} = 5.0V, GND = 0V, T_A = -55°C to +125°C)

Parameter	Sym	Conditions	-15		-17		-20		-25		Units
			Min	Max	Min	Max	Min	Max	Min	Max	
Input Leakage Current	I _{LI}	V _{CC} = 5.5, V _{IN} = GND to V _{CC}		10		10		10		10	μA
Output Leakage Current	I _{LO}	\overline{CS} = V _{IH} , \overline{OE} = V _{IH} , V _{OUT} = GND to V _{CC}		10		10		10		10	μA
Operating Supply Current	I _{CC}	\overline{CS} = V _{IL} , \overline{OE} = V _{IH} , f = 5MHz, V _{CC} = 5.5		600		600		600		600	mA
Standby Current	I _{SB}	\overline{CS} = V _{IH} , \overline{OE} = V _{IH} , f = 5MHz, V _{CC} = 5.5		80		80		80		60	mA
Output Low Voltage	V _{OL}	I _{OL} = 8mA, V _{CC} = 4.5		0.4		0.4		0.4		0.4	V
Output High Voltage	V _{OH}	I _{OH} = -4.0mA, V _{CC} = 4.5	2.4		2.4		2.4		2.4		V

Parameter	Sym	Conditions	-35		-45		-55		Units
			Min	Max	Min	Max	Min	Max	
Input Leakage Current	I _{LI}	V _{CC} = 5.5, V _{IN} = GND to V _{CC}		10		10		10	μA
Output Leakage Current	I _{LO}	\overline{CS} = V _{IH} , \overline{OE} = V _{IH} , V _{OUT} = GND to V _{CC}		10		10		10	μA
Operating Supply Current	I _{CC}	\overline{CS} = V _{IL} , \overline{OE} = V _{IH} , f = 5MHz, V _{CC} = 5.5		600		600		600	mA
Standby Current	I _{SB}	\overline{CS} = V _{IH} , \overline{OE} = V _{IH} , f = 5MHz, V _{CC} = 5.5		60		60		60	mA
Output Low Voltage	V _{OL}	I _{OL} = 2.1mA, V _{CC} = 4.5		0.4		0.4		0.4	V
Output High Voltage	V _{OH}	I _{OH} = -1.0mA, V _{CC} = 4.5	2.4		2.4		2.4		V

NOTE: DC test conditions: V_{IH} = V_{CC} - 0.3V, V_{IL} = 0.3V

DATA RETENTION CHARACTERISTICS*

(T_A = -55°C to +125°C), (T_A = -40°C to +85°C)

Characteristic	Sym	Conditions	Min	Typ	Max	Units
Data Retention Voltage	V _{CC}	V _{CC} = 2.0V	2	-	-	V
Data Retention Quiescent Current	I _{CCDR}	CS ≥ V _{CC} - 0.2V	-	1	4	mA
Chip Disable to Data Retention Time (1)	T _{CDR}	V _{IN} ≥ V _{CC} - 0.2V	0	-	-	ns
Operation Recovery Time (1)	T _R	or V _{IN} ≤ 0.2V	T _{RC}	-	-	ns

NOTE: Parameter guaranteed, but not tested.

*Low Power Data Retention available only in G2T/E Package Type.



AC CHARACTERISTICS

(V_{CC} = 5.0V, GND = 0V, T_A = -55°C to +125°C)

Parameter	Symbol	-15		-17		-20		-25		-35		-45		-55		Units
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Read Cycle Time	t _{RC}	15		17		20		25		35		45		55		ns
Address Access Time	t _{AA}		15	17		20		25		35		45		55		ns
Output Hold from Address Change	t _{OH}	0		0		0		0		0		0		0		ns
Chip Select Access Time	t _{ACS}		15	17		20		25		35		45		55		ns
Output Enable to Output Valid	t _{OE}		10	10		12		15		20		25		30		ns
Chip Select to Output in Low Z	t _{CLZ} ¹	3		3		3		3		3		3		3		ns
Output Enable to Output in Low Z	t _{OLZ} ¹	0		0		0		0		0		0		0		ns
Chip Disable to Output in High Z	t _{CHZ} ¹		12	12		12		12		20		20		20		ns
Output Disable to Output in High Z	t _{OHZ} ¹		12	12		12		12		20		20		20		ns

1. This parameter is guaranteed by design but not tested.

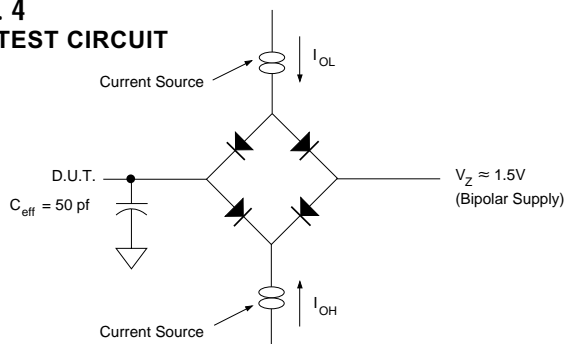
AC CHARACTERISTICS

(V_{CC} = 5.0V, GND = 0V, T_A = -55°C to +125°C)

Parameter	Symbol	-15		-17		-20		-25		-35		-45		-55		Units
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Write Cycle Time	t _{WC}	15		17		20		25		35		45		55		ns
Chip Select to End of Write	t _{CW}	14		14		15		20		25		30		45		ns
Address Valid to End of Write	t _{AW}	14		15		15		20		25		30		45		ns
Data Valid to End of Write	t _{DW}	10		10		12		15		20		25		25		ns
Write Pulse Width	t _{WP}	14		14		15		20		25		30		45		ns
Address Setup Time	t _{AS}	0		0		0		0		0		0		0		ns
Address Hold Time	t _{AH}	0		0		0		0		0		0		0		ns
Output Active from End of Write	t _{OW} ¹	3		3		3		3		4		4		4		ns
Write Enable to Output in High Z	t _{WHZ} ¹		10	10		12		15		20		25		25		ns
Data Hold Time	t _{DH}	0		0		0		0		0		0		0		ns

1. This parameter is guaranteed by design but not tested.

FIG. 4
AC TEST CIRCUIT



AC TEST CONDITIONS

Parameter	Typ	Unit
Input Pulse Levels	V _{IL} = 0, V _{IH} = 3.0	V
Input Rise and Fall	5	ns
Input and Output Reference Level	1.5	V
Output Timing Reference Level	1.5	V

NOTES:

V_Z is programmable from -2V to +7V.
 I_{OL} & I_{OH} programmable from 0 to 16mA.
 Tester Impedance Z₀ = 75 Ω.
 V_Z is typically the midpoint of V_{OH} and V_{OL}.
 I_{OL} & I_{OH} are adjusted to simulate a typical resistive load circuit.
 ATE tester includes jig capacitance.



FIG. 5
TIMING WAVEFORM - READ CYCLE

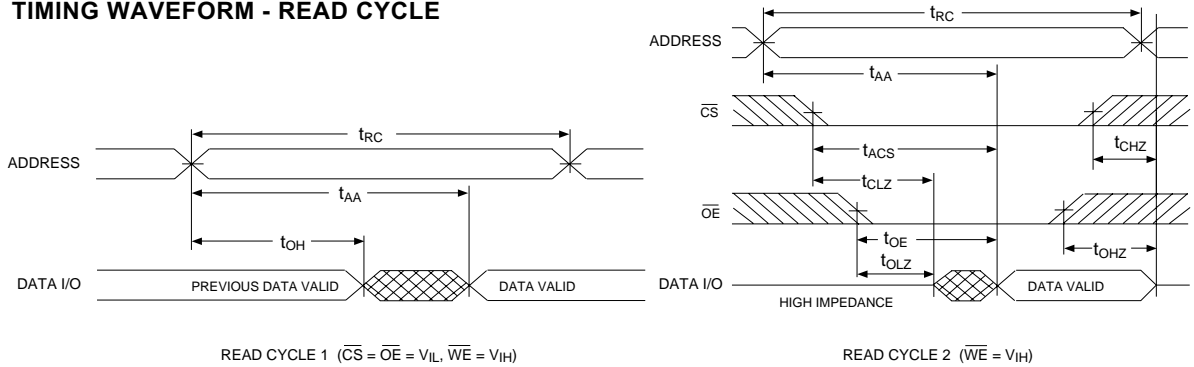


FIG. 6
WRITE CYCLE - \overline{WE} CONTROLLED

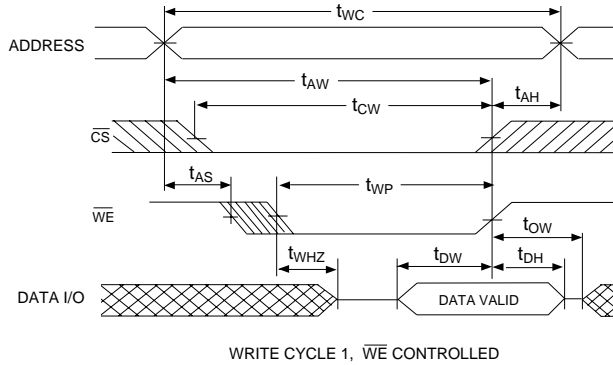
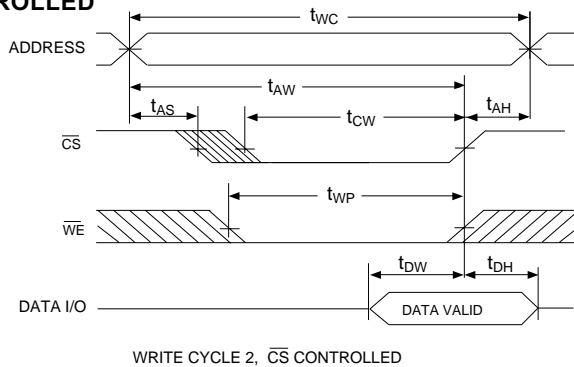
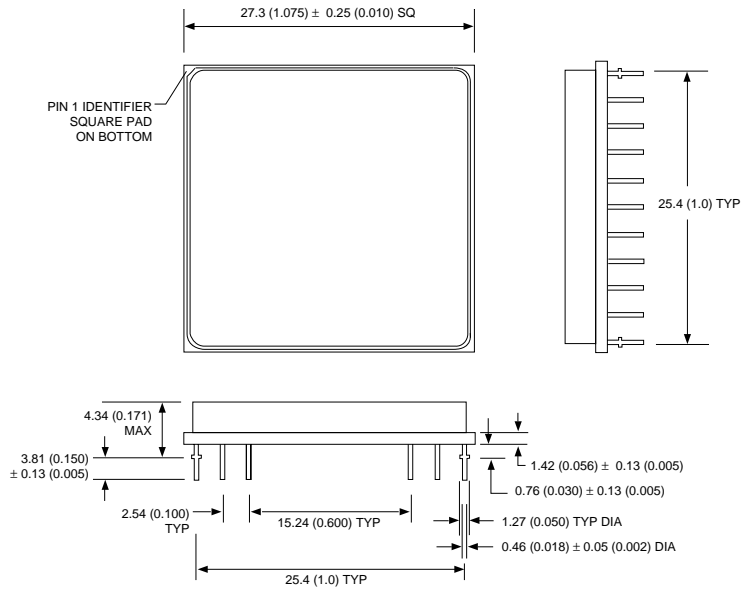


FIG. 7
WRITE CYCLE - \overline{CS} CONTROLLED



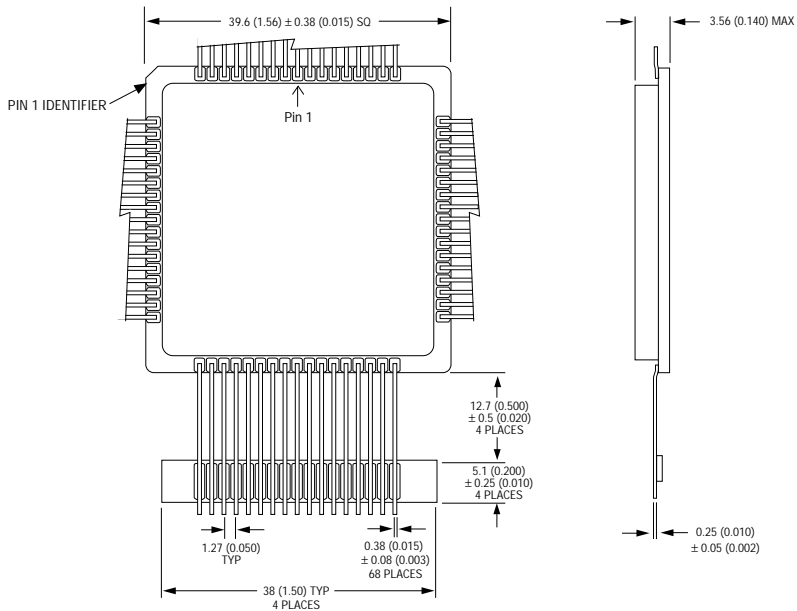


PACKAGE 400: 66 PIN, PGA TYPE, CERAMIC HEX-IN-LINE PACKAGE, HIP (H1/G)



ALL LINEAR DIMENSIONS ARE MILLIMETERS AND PARENTHETICALLY IN INCHES

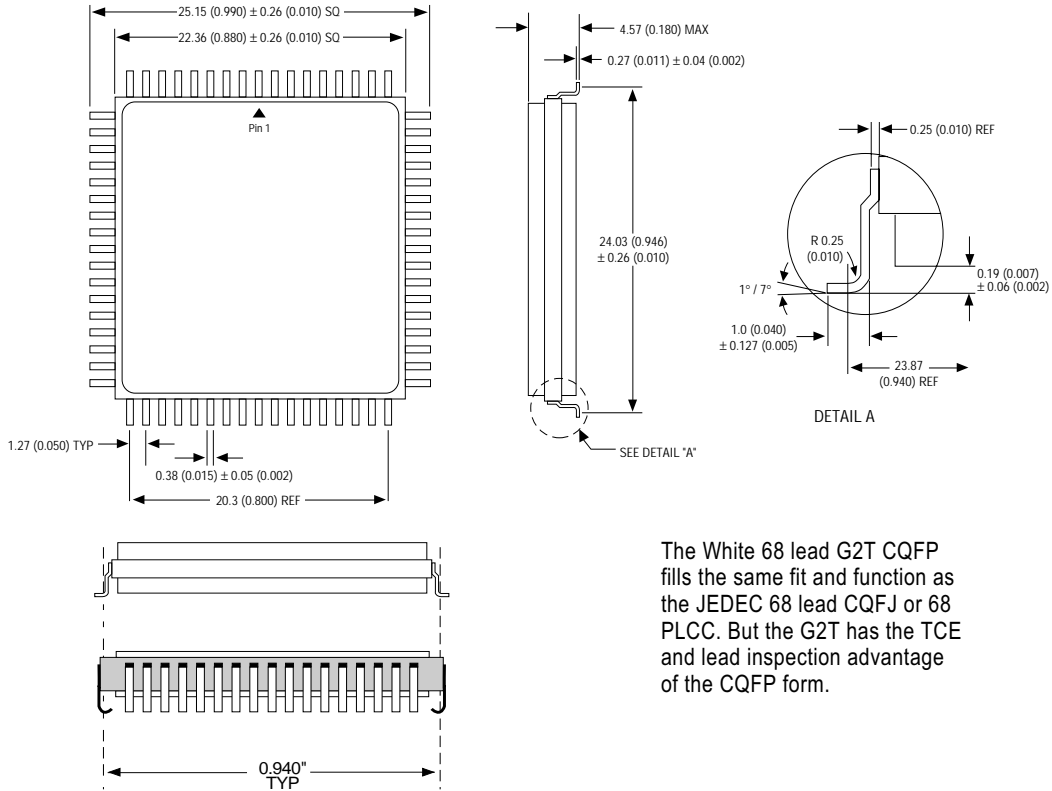
PACKAGE 502: 68 LEAD, CERAMIC QUAD FLAT PACK, LOW PROFILE CQFP (G4T)



ALL LINEAR DIMENSIONS ARE MILLIMETERS AND PARENTHETICALLY IN INCHES



PACKAGE 509: 68 LEAD, LOW PROFILE CERAMIC QUAD FLAT PACK, CQFP (G2T/E)



The White 68 lead G2T CQFP fills the same fit and function as the JEDEC 68 lead CQFJ or 68 PLCC. But the G2T has the TCE and lead inspection advantage of the CQFP form.

ALL LINEAR DIMENSIONS ARE MILLIMETERS AND PARENTHETICALLY IN INCHES



ORDERING INFORMATION

NOTE: For non-SMD new designs, please use the WS128K32-XXX part number for inquiries and orders.

W S 128K 32 X - XXX X X X

LEAD FINISH:

- Blank = Gold plated leads
- A = Solder dip leads

DEVICE GRADE:

- Q = MIL-STD-883 Compliant
- M = Military Screened -55°C to +125°C
- I = Industrial -40°C to +85°C
- C = Commercial 0°C to +70°C

PACKAGE TYPE:

- H1 = 1.075" sq. Ceramic Hex-In-line Package, HIP (Package 400)
- G2T = 22.4mm Ceramic Quad Flat Pack, Low Profile CQFP (Package 509)
- G4T = 40 mm Low Profile CQFP (Package 502)

ACCESS TIME (ns)

IMPROVEMENT MARK:

- N = No Connect at pin 8, 21, 28 and 39 in HIP for Upgrades
- L = Low Power *

ORGANIZATION, 128Kx32

User configurable as 256Kx16 or 512Kx8

SRAM

WHITE MICROELECTRONICS

EDI 8 C 32 128 C X X X

ELECTRONIC DESIGNS

SRAM

CERAMIC MCM

ORGANIZATION, 128Kx32

TECHNOLOGY:

- C = CMOS Standard Power
- LP = Low Power *

ACCESS TIME (ns)

PACKAGE TYPE:

- E = 22.4mm Ceramic Quad Flat Pack, Low Profile CQFP (Package 509)
- G = 1.075" sq. Ceramic Hex-In-line Package, HIP (Package 400)

DEVICE GRADE:

- B = MIL-STD-883 Compliant
- M = Military Screened -55°C to +125°C
- I = Industrial -40°C to +85°C
- C = Commercial 0°C to +70°C

* Low Power Data Retention only available in G2T/E Package Type



DEVICE TYPE	SPEED	PACKAGE	SMD NO.
128K x 32 SRAM Module	55ns	66 pin HIP (H1)	5962-93187 05H5X
128K x 32 SRAM Module	45ns	66 pin HIP (H1)	5962-93187 06H5X
128K x 32 SRAM Module	35ns	66 pin HIP (H1)	5962-93187 07H5X
128K x 32 SRAM Module	25ns	66 pin HIP (H1)	5962-93187 08H5X
128K x 32 SRAM Module	20ns	66 pin HIP (H1)	5962-93187 09H5X
128K x 32 SRAM Module	17ns	66 pin HIP (H1)	5962-93187 10H5X
128K x 32 SRAM Module	15ns	66 pin HIP (H1)	5962-93187 11H5X
128K x 32 SRAM Module	55ns	68 lead CQFP Low Profile (G4T)	5962-95595 05HYX
128K x 32 SRAM Module	45ns	68 lead CQFP Low Profile (G4T)	5962-95595 06HYX
128K x 32 SRAM Module	35ns	68 lead CQFP Low Profile (G4T)	5962-95595 07HYX
128K x 32 SRAM Module	25ns	68 lead CQFP Low Profile (G4T)	5962-95595 08HYX
128K x 32 SRAM Module	20ns	68 lead CQFP Low Profile (G4T)	5962-95595 09HYX
128K x 32 SRAM Module	17ns	68 lead CQFP Low Profile (G4T)	5962-95595 10HYX
128K x 32 SRAM Module	15ns	68 lead CQFP Low Profile (G4T)	5962-95595 11HYX
128K x 32 SRAM Module	55ns	68 lead CQFP/J (G2T)	5962-95595 05HMX
128K x 32 SRAM Module	45ns	68 lead CQFP/J (G2T)	5962-95595 06HMX
128K x 32 SRAM Module	35ns	68 lead CQFP/J (G2T)	5962-95595 07HMX
128K x 32 SRAM Module	25ns	68 lead CQFP/J (G2T)	5962-95595 08HMX
128K x 32 SRAM Module	20ns	68 lead CQFP/J (G2T)	5962-95595 09HMX
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